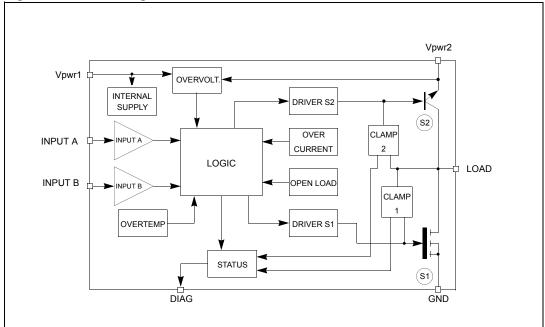
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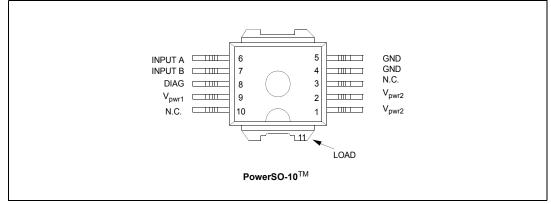


## 1 Block diagram and pin description



### Figure 1. Block diagram







# 2 Electrical specifications

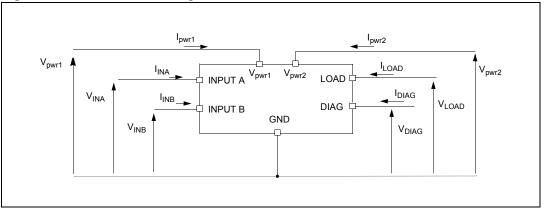


Figure 3. Current and voltage conventions

## 2.1 Absolute maximum ratings

Table 2.	Absolute maximum ratings		
Symbol	Parameter	Value	Unit
V <sub>load</sub>	Maximum DC load voltage	Internally clamped	V
I <sub>load</sub>	Maximum DC load current	Internally clamped	А
I <sub>rload</sub>	Reverse load current, T <sub>case</sub> = 25 °C	-10	А
Ec	Maximum clamping energy, T <sub>case</sub> = 150 °C, f = 40 Hz, 1000 hours (f: input A frequency)	100	mJ
Ec	Maximum clamping energy, T <sub>case</sub> = -40 °C, f = 75 Hz, 5 minutes (f: input A frequency)	100	mJ
l <sub>in</sub>	Inputs current	+/-10	mA
I <sub>diag</sub>	Diagnostic output current	+/-10	mA
$V_{ESD}$	Electrostatic discharge (R = 1.5 k $\Omega$ , C = 100 pF, all pins)	2000	V
V <sub>pwr1</sub>	Power voltage 1	60	V
V <sub>pwr2</sub>	Power voltage 2	60	V
R <sub>Vpwr</sub>	Reverse power voltage	-0.3	V
Тj	Junction operating temperature	-40 to 150 <sup>(1)</sup>	°C
T <sub>stg</sub>	Storage temperature	-55 to 150	°C
V <sub>in</sub>	Input voltages	8	V
V <sub>diag</sub>	Diagnostic output voltage	8	V
Cload	Load capacity	1	μF

 Table 2.
 Absolute maximum ratings

1. Higher temperature is allowed during a short time before thermal shutdown. Permanent operation above °C 150 is not allowed.



## 2.2 Thermal data

### Table 3. Thermal data

Symbol	Parameter	PowerSO-10	Unit
R <sub>thj-case</sub>	Thermal resistance junction-case max	1.67	°C/W
R <sub>thj-amb</sub> Thermal resistance junction-ambient max <sup>(1)</sup>		50	°C/W

1. When mounted using minimum recommented pad size on FR-4 board.

## 2.3 Electrical characteristics

10 V < V\_{PWR1} < 18 V; -40 °C < T\_J < 150 °C unless otherwise specified

Symbol	Parameter	Test conditions	Min	Тур	Max	Unit
Power						
V <sub>pwr1</sub>	Operating voltage		6	13	24	V
R <sub>on1</sub>	On-state resistance (excitation path)	I <sub>load</sub> = I <sub>n</sub> = 5 A V <sub>inA</sub> = V <sub>inB</sub> = 5 V			0.2	Ω
R <sub>on2</sub>	On-state resistance (recirculation path)	V <sub>pwr1</sub> = 13 V; I <sub>load</sub> = I <sub>n</sub> = 5 A V <sub>inA</sub> = 5 V; V <sub>inB</sub> = GND			0.4	Ω
V <sub>ce(sat)</sub>	Saturation voltage of bipolar S2	$I_{load} = I_n = 5 A$ $V_{pwr1} = V_{pwr2} = 13 V$ $I_{load} = 10 A; T_J > 125 °C$ $V_{pwr1} = V_{pwr2} = 13 V$			2 2	V V
I <sub>sq</sub>	Supply quiescent current	V <sub>pwr1</sub> = 13 V; V <sub>inA</sub> = V <sub>inB</sub> = 5 V			25	mA
I <sub>lk</sub>	Output leakage current	$V_{pwr1}$ = 18 V; $V_{inA}$ = $V_{inB}$ = GND			5	mA
I <sub>off</sub>	Off-state supply current	$V_{inA} = V_{inB} = GND$ $V_{pwr1} = not connected$ $10 V < V_{pwr2} < 24 V$ $T_J = 25 °C$			50	μΑ
Switching	(excitation path)		•			
t <sub>d(on)</sub>	Turn-on delay time	$R_{load}$ = 2.5 $\Omega$ ; $V_{inA}$ = 5 V (see <i>Figure 4</i> )			50	μs
t <sub>r</sub>	Rise time of output current	R <sub>load</sub> = 2.5 Ω; V <sub>inA</sub> = 5 V (see <i>Figure 4</i> )	1		20	μs
t <sub>d(off)</sub>	Turn-off delay time	R <sub>load</sub> = 2.5 Ω; V <sub>inA</sub> = 5 V (see <i>Figure 4</i> )			50	μs
t <sub>f</sub>	Fall time of output current	$R_{load} = 2.5 \Omega; V_{inA} = 5 V$ (see <i>Figure 4</i> )	1		20	μs
Logic inpu	ıt					
V <sub>il</sub>	Input low level voltage				1.5	V

### Table 4. Electrical characteristics



	Liectrical characteris		-			
Symbol	Parameter	Test conditions	Min	Тур	Мах	Unit
V <sub>ih</sub>	Input high level voltage		3.5			V
V <sub>i(hyst)</sub>	Input hysteresis voltage		0.5	0.8	2	V
V <sub>i(CL)</sub>	Input clamp voltage	I <sub>in</sub> = 10 mA	8	9.5	11	V
I <sub>in</sub>	Input current	$V_{inA} = V_{inB} = 2 V$ $V_{inA} = V_{inB} = 5 V$	20		250	μA μA
Protection	s and diagnostics					
T <sub>tsd</sub>	Thermal shutdown temperature		160	180	200	°C
l <sub>lim</sub>	Current cut off level		15		30	Α
Vov	Overvoltage threshold	$V_{inA} = V_{inB} = 5 V$	27			V
V <sub>diag</sub>	Status output voltage	Diagnostic output active (low) I <sub>diag</sub> = 2 mA			0.5	V
V <sub>diag(CL)</sub>	Status output clamp voltage	I <sub>diag</sub> = 10 mA	8	9.5	11	V
Τ <sub>d</sub>	Status propagation delay	Demagnetization mode (fast turn-off) V <sub>diag</sub> = 1 V (see <i>Figure 6</i> )			70	μs
V <sub>cl1</sub>	Switch S1 detection clamp	$I_{load} = I_n = 5 A$	60	70	80	V
V <sub>cl2</sub>	Output inductive clamp voltage	$I_{load} = I_n = 5 A$	24	28.5	33	V
V <sub>fb</sub>	Flyback diagnostic threshold	Demagnetization mode (fast turn-off) $V_{cl} = V_{cl1}$ or $V_{cl2}$	V <sub>cl</sub> -5		V <sub>cl</sub>	V
I <sub>ol</sub>	Open-load current level		5		700	mA

### Table 4. Electrical characteristics (continued)

### Table 5. Truth table

Conditions	In A	In B	S1	S2
Standby modes	L	L	Off	Off
	L	Н	Off	Off
Excitation mode	Н	Н	On	Off
Recirculation mode	Н	L	Off	On
Demagnetization mode				
(fast turn-off)				
$V_{pwr2} + V_{cl2} < V_{cl1}$	L	L	Off	On
$V_{pwr2} + V_{cl2} > V_{cl1}$	L	L	On	On
Thermal shutdown	Н	Н	Off	On
Current cut off	Н	Н	Off	On
Open-load	Se	e open-load waveforr	ns on <i>Figure 5</i>	
Overvoltage	Н	Н	Off	On



#### 3 **Functional description**

#### 3.1 Current cut off

When the load current rise above the current cut off level, S1 is automatically switched off and the devices operates in recirculation mode (S2 active). S1 is latched off until A goes low and high again.

This default is not displayed by diagnostic flag.

#### 3.2 **Open-load**

If the load current is below the open-load current level, the flag of the open-load block is activated but this default is displayed by the diagnostic output on the falling edge of input B and the diagnostic output is latched at low level until input A goes low and high again. In case an open-load is detected during an active phase of input B, but disappears before a falling edge of input B, this default is not dispayed by the diagnostic flag (see open-load waveforms on Figure 5).

#### 3.3 Thermal shutdown

The device is internally protected against over temperatures by the thermal circuit protection. When the device junction temperature exceeds the protection limit, S1 is automatically switched off. Therefore the device operates in recirculation mode (S2 active). S1 remain latched off until V<sub>pwr1</sub> goes low and high again. This default is not dispayed by the diagnostic flag.

#### 3.4 Overvoltage

During the on-state of S1 switch, if  $V_{pwr1}$  or  $V_{pwr2}$  is rising above the threshold detection S1 is automatically switched off, therefore the device operates in recirculation mode.

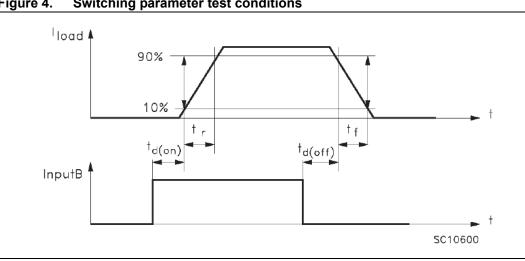
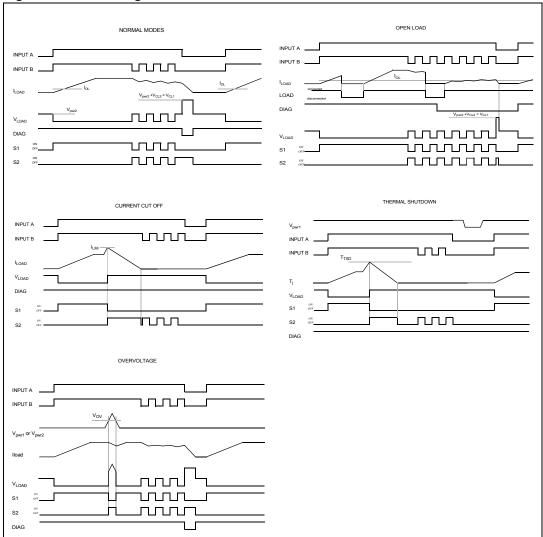


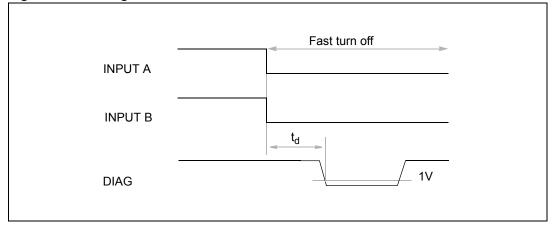
Figure 4. Switching parameter test conditions





### Figure 5. Switching waveforms

Figure 6. Demagnetization mode





## 4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK<sup>®</sup> packages, depending on their level of environmental compliance. ECOPACK<sup>®</sup> specifications, grade definitions and product status are available at: <u>www.st.com</u>.

ECOPACK<sup>®</sup> is an ST trademark.

### 4.1 PowerSO-10 mechanical data

 Table 6.
 PowerSO-10 mechanical data

Dim	mm			inch			
Dim.	Min.	Тур.	Max.	Min.	Тур.	Max.	
Α	3.35		3.65	0.132		0.144	
A1	0.00		0.10	0.000		0.004	
В	0.40		0.60	0.016		0.024	
с	0.35		0.55	0.013		0.022	
D	9.40		9.60	0.370		0.378	
D1	7.40		7.60	0.291		0.300	
E	9.30		9.50	0.366		0.374	
E1	7.20		7.40	0.283		0.291	
E2	7.20		7.60	0.283		0.300	
E3	6.10		6.35	0.240		0.250	
E4	5.90		6.10	0.232		0.240	
е		1.27			0.050		
F	1.25		1.35	0.049		0.053	
Н	13.80		14.40	0.543		0.567	
h		0.50			0.002		
L	1.20		1.80	0.047		0.071	
q		1.70			0.067		
α	0°		8°				



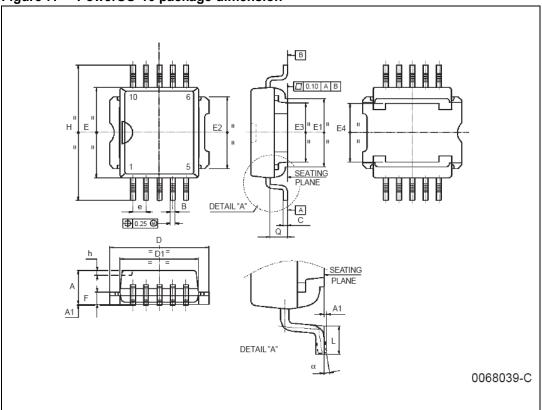


Figure 7. PowerSO-10 package dimension

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# 5 Revision history

### Table 7.Document revision history

Date	Revision	Changes
10-Jun-2009	1	Initial release.
20-Sep-2013	2	Updated Disclaimer.



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